

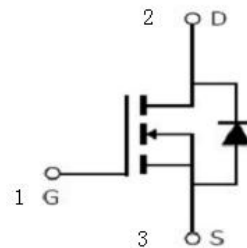
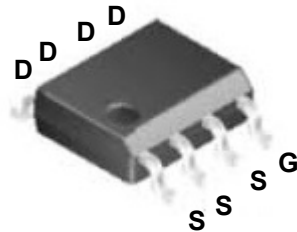
General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

V_{DS}	40V
I_D (at $V_{GS}=10V$)	9A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	7m Ω (Typ)

SOP8



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	40	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Drain Current-Continuous	TC=25 $^\circ\text{C}$	I_D	9	A
	TC=100 $^\circ\text{C}$	I_D	5.7	A
Maximum Power Dissipation	P_D	1.47	W	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta JC}$		1.1	$^\circ\text{C} / \text{W}$
Thermal Resistance unction-to-Ambient	$R_{\theta JA}$		62	$^\circ\text{C} / \text{W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =8A		7	9	mΩ
		V _{GS} =4.5V, I _D =4A		9.5	13	mΩ
DYNAMIC PARAMETERS						
C _{ISS}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, F=1.0MHz		1200		pF
C _{OSS}	Output Capacitance			130		pF
C _{RSS}	Reverse Transfer Capacitance			55		pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-on Delay Time	V _{DD} =15V, I _D =1A, V _{GS} =10V, R _G =3.3Ω		13.2		nS
t _r	Turn-on Rise Time			2.2		nS
t _{d(off)}	Turn-Off Delay Time			72		nS
t _f	Turn-Off Fall Time			4.5		nS
Q _g	Total Gate Charge	V _{DS} =20V, I _D =8A, V _{GS} =4.5V		12.2		nC
Q _{gs}	Gate-Source Charge			3.3		nC
Q _{gd}	Gate-Drain Charge			6.7		nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _{SD} =1A		0.72	1.3	V
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		2.2		Ω

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

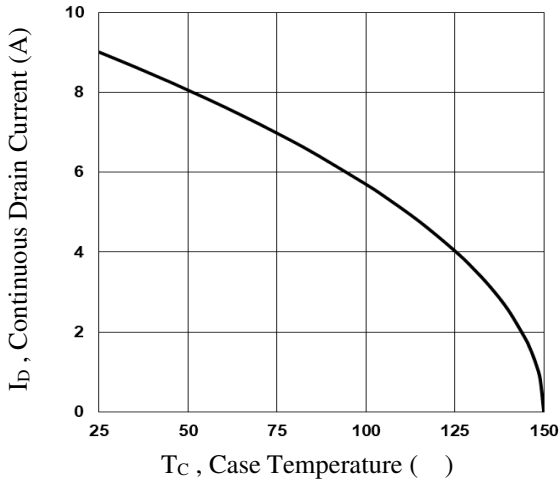


Fig.1 Continuous Drain Current vs. T_c

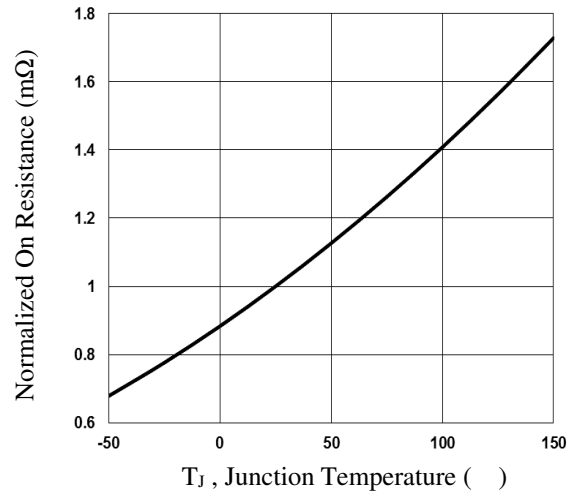


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

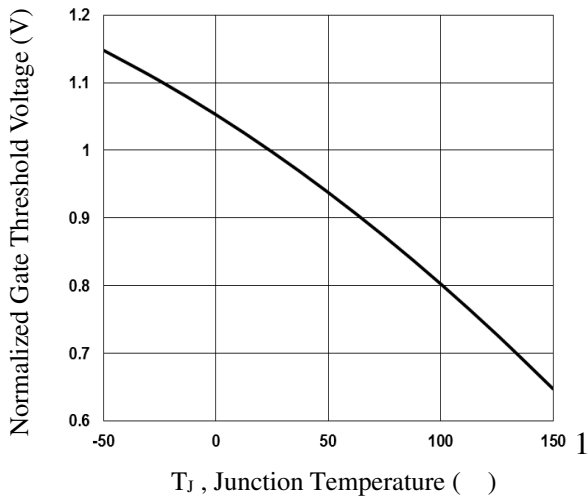


Fig.3 Normalized V_{th} vs. T_j

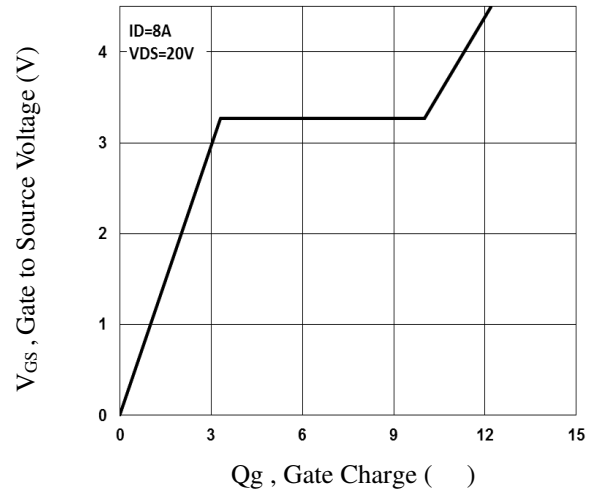


Fig.4 Gate Charge Waveform

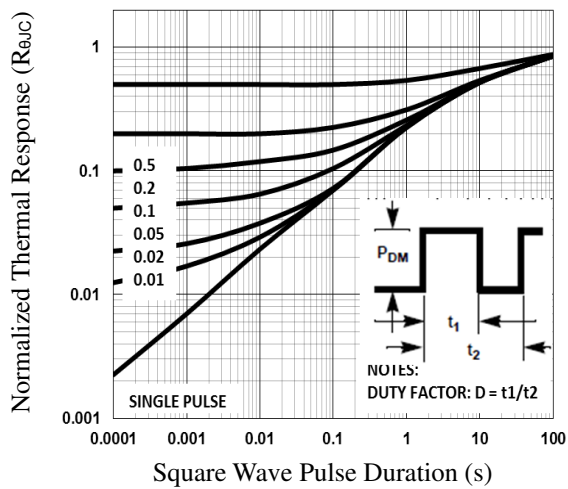


Fig.5 Normalized Transient Impedance

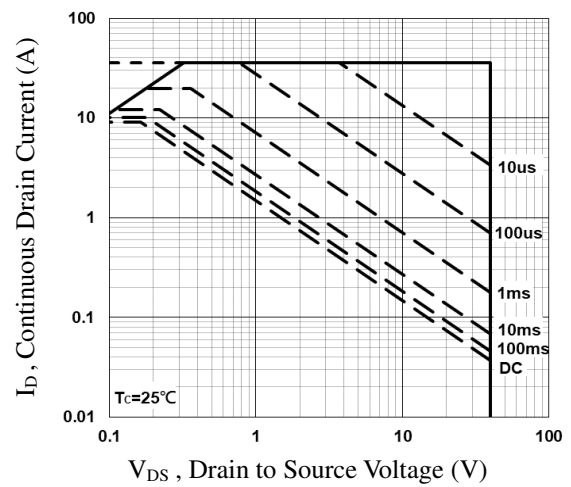


Fig.6 Maximum Safe Operation Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

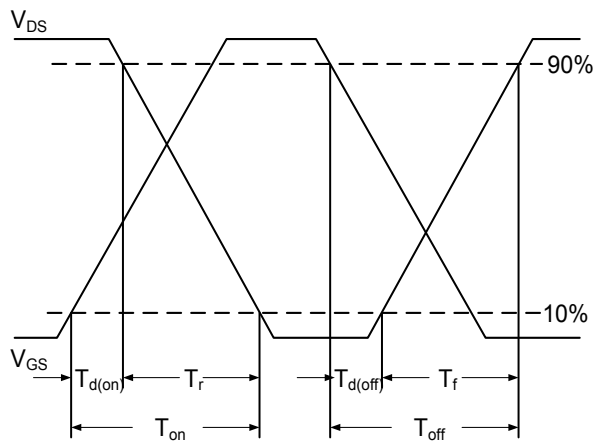


Fig.7 Switching Time Waveform

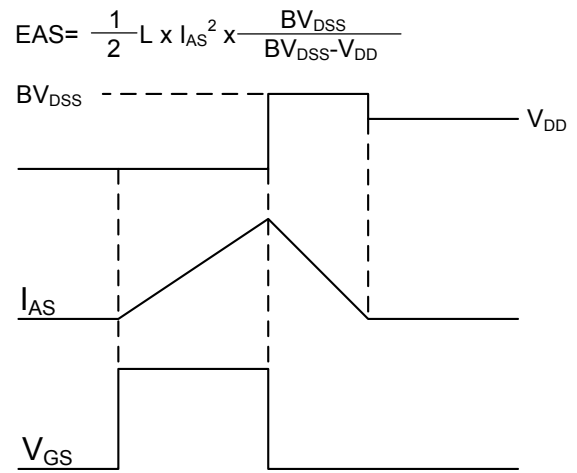
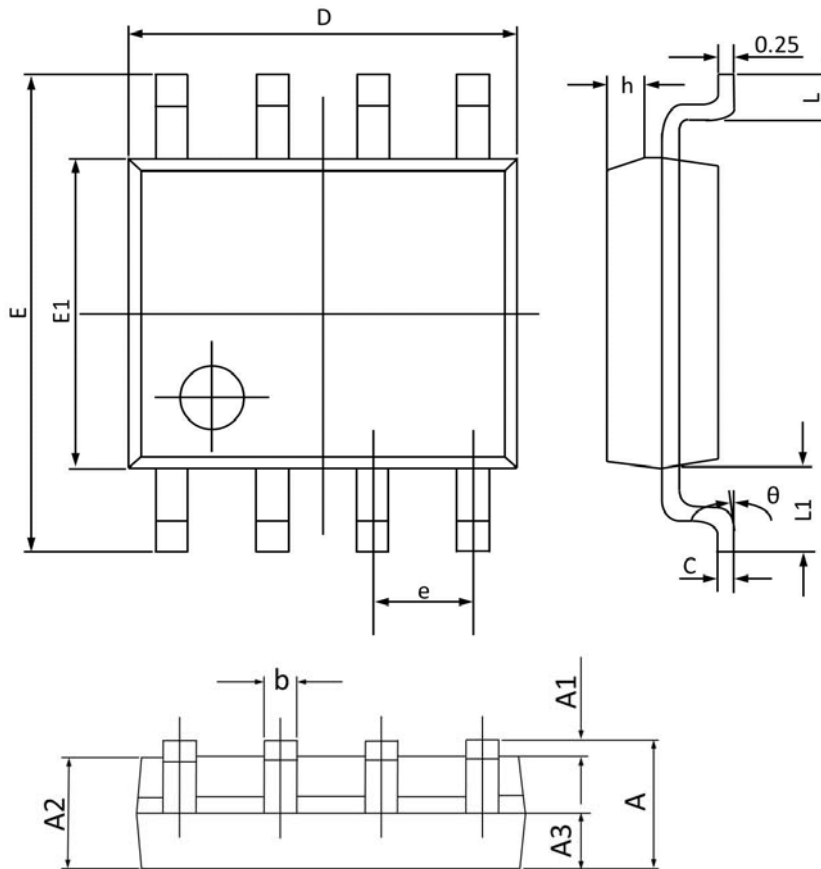


Fig.8 EAS Waveform

SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°

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